

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-206021

(43)Date of publication of application : 26.07.2002

(51)Int.Cl.

C08G 59/62  
C08K 3/00  
C08K 5/5465  
C08K 9/06  
C08L 63/00  
C09K 3/10  
H01L 23/29  
H01L 23/31

(21)Application number : 2001-003184

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(22)Date of filing : 11.01.2001

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## (54) EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide an epoxy resin composition for sealing semiconductor, having excellent strength at the heated time, having excellent adhesion to various kinds of members such as a semiconductor element and a lead frame, and excellent solder resistance when the member is mounted on a substrate, especially at a solder-treating temperature higher than that in a conventional method, and further having excellent adhesion to a pre-plating frame of Ni, Ni-Pd, Ni-Pd-Au or the like.

**SOLUTION:** This epoxy resin composition for sealing the semiconductor is characterized in that the composition consists essentially of (A) an epoxy resin, (B) a phenol resin, (C) an organic compound having a silanol group and an isocyanate group in the same molecule, and/or a hydrolyzed product of the organic compound, (D) an inorganic filler and (E) a curing accelerator.

## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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(19) 日本国特許庁 (J P)

(12) 公開特許公報 (A)

(11) 特許出願公開番号

特開2002-206021

(P2002-206021A)

(43) 公開日 平成14年7月26日 (2002.7.26)

| (51) Int.Cl. <sup>7</sup>            | 識別記号 | F I           | テマコード <sup>*</sup> (参考) |
|--------------------------------------|------|---------------|-------------------------|
| C 0 8 G 59/62                        |      | C 0 8 G 59/62 | 4 H 0 1 7               |
| C 0 8 K 3/00                         |      | C 0 8 K 3/00  | 4 J 0 0 2               |
| 5/5465                               |      | 5/5465        | 4 J 0 3 6               |
| 9/06                                 |      | 9/06          | 4 M 1 0 9               |
| C 0 8 L 63/00                        |      | C 0 8 L 63/00 | C                       |
| 審査請求 未請求 請求項の数 8 O L (全 11 頁) 最終頁に続く |      |               |                         |

(21) 出願番号 特願2001-3184(P2001-3184)

(22) 出願日 平成13年1月11日 (2001.1.11)

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(54) 【発明の名称】 エポキシ樹脂組成物及び半導体装置

(57) 【要約】

【課題】 熱時強度に優れ、半導体素子、リードフレーム等の各種部材との接着性、基板実装時の耐半田性、特に半田処理温度が従来よりも高い場合の耐半田性に優れ、又Ni、Ni-Pd、Ni-Pd-Au等のブリブレーティングフレームとの密着性に優れた半導体封止用エポキシ樹脂組成物を提供すること。

【解決手段】 (A) エポキシ樹脂、(B) フェノール樹脂、(C) シラノール基とイソシアネート基を同一分子内に有する有機化合物及び/又は該有機化合物の加水分解物、(D) 無機充填材、及び(E) 硬化促進剤を必須成分とすることを特徴とする半導体封止用エポキシ樹脂組成物。